MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

SPMAA–A26 / 26LD, PDD STD, CERAMIC TYPE, STANDARD DUAL FORM
CASE MODFA
ISSUE O
DATE 31 JAN 2017

NOTES: UNLESS OTHERWISE SPECIFIED
A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
B) ALL DIMENSIONS ARE IN MILLIMETERS
C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
D) ( ) IS REFERENCE

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DOCUMENT NUMBER: 98AON13553G
STATUS: ON SEMICONDUCTOR STANDARD
NEW STANDARD:
DESCRIPTION: SPMAA–A26 / 26LD, PDD STD, CERAMIC TYPE, STANDARD DUAL
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Released for Production from Fairchild MKT−MOD26AA to ON Semiconductor. Req. by I. Hyland.

31 Jan 2017